TOSHIBA Photocoupler IRED & Photo-Triac

# TLP360J

Triac Drivers
Programmable Controllers
AC-Output Modules
Solid State Relays

TOSHIBA TLP360J consists of a photo-triac optically coupled to an infrared emitting diode in a four-lead plastic DIP package.

Peak off-state voltage: 600 V (min)
Trigger LED current: 10 mA (max)
On-state current: 100 mA (max)
Isolation voltage: 5000 Vrms (min)

•UL-recognized: UL 1577, File No.E67349

•cUL-recognized : CSA Component Acceptance Service No.5A

File No.E67349

•CQC-approved: GB4943.1, GB8898 Japan Factory •VDE-approved: EN 60747-5-5, EN 62368-1 (Note 1)

Note 1: When a VDE approved type is needed, please designate the **Option(D4)** 

Weight: 0.26 g (typ.)

· Construction mechanical rating

Creepage distance 7.0 mm (min)
Clearance 7.0 mm (min)
Insulation thickness 0.4 mm (min)

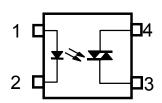
#### Trigger LED Current

	Trigger LED			
Classification (Note 1)	V <sub>T</sub> = 6 V,	Marking of classification		
(Note 1)	Min	Max	Classification	
(IFT7)	_	7	T7	
Standard	_	10	T7, blank	

Note 1: Example: "(IFT7)"; "TLP360J(IFT7)"

Note: When specifying the application type name for certification testing, be sure to use the standard product type name, e.g. TLP360J(IFT7): TLP360J.

#### Pin Configuration (top view)



1: Anode

2: Cathode

3: Triac Terminal

4: Triac Terminal

Start of commercial production 2003-06

## Absolute Maximum Ratings (Ta = 25°C)

	Characteristic		Symbol	Rating	Unit	
	Forward current		lF	50	mA	
	Forward current derating (Ta ≥ 53°C)		ΔI <sub>F</sub> /°C	-0.7	mA /°C	
	Peak forward current (100 µs pulse, 100 pps)	IFP	1	Α		
LED	Reverse voltage		VR	5	V	
	Diode power dissipation		$P_D$	100	mW	
	Diode power dissipation derating (Ta ≥ 53°C)		ΔP <sub>D</sub> /°C	-1.4	mW/°C	
	Junction temperature		Tj	125	°C	
	Off-state output terminal voltage	V <sub>DRM</sub>	600	V		
	On-state RMS current	Ta = 25°C	IT(DMO)	100	mA	
On-state	On-state Rivis current	Ta = 70°C	IT(RMS)	50		
ō	On-state current derating (Ta ≥ 25°C)		ΔIT/°C	-1.1	mA /°C	
Detector	Peak on-state current (100 µs pulse, 120 pps)		ITP	2	Α	
۵	Peak non-repetitive surge current (Pw = 10 ms)		I <sub>TSM</sub>	1.2	Α	
	Output power dissipation		Ро	300	mW	
	Output power dissipation derating (Ta ≥ 25°C)		ΔP <sub>o</sub> /°C	-2.0	mW / °C	
	Junction temperature		Tj	115	°C	
Sto	Storage temperature range			-55 to 125	°C	
Оре	Operating temperature range		Topr	-40 to 100	°C	
Lea	d soldering temperature (10 s)		T <sub>sol</sub>	260	°C	
Isol	ation voltage (AC, 60 s, R.H. ≤ 60 %)	(Note 1)	BVs	5000	Vrms	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Pins 1 and 2 are shorted together and pins 3 and 4 are shorted together.

#### **Recommended Operating Conditions**

Characteristic	Symbol	Min	Тур.	Max	Unit
Supply voltage	V <sub>A</sub> C	_	_	240	$V_{ac}$
Forward current	lF	15	20	25	mA
Peak on-state current	ITP	_	_	1	Α
Operating temperature	T <sub>opr</sub>	-25		85	°C

Note: Recommended operating conditions are given as a design guideline to obtain expected performance of the device. Additionally, each item is an independent guideline respectively. In developing designs using this product, please confirm specified characteristics shown in this document.

## **Electrical Characteristics (Ta = 25°C)**

	Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
	Forward voltage	VF	I <sub>F</sub> = 10 mA		1.15	1.3	V
LED	Reverse current	I <sub>R</sub>	V <sub>R</sub> = 5 V	_	_	10	μΑ
	Capacitance	CT	VF = 0 V, f = 1 MHz	_	30	_	pF
	Peak off-state current	I <sub>DRM</sub>	V <sub>DRM</sub> = 600 V	_	10	1000	nA
_	Peak on-state voltage	V <sub>TM</sub>	I <sub>TM</sub> = 100 mA	_	1.7	3.0	V
Detector	Holding current	lΗ	_	_	1.0	_	mA
Det	Critical rate of rise of off-state voltage	dv/dt	Vin = 240 Vrms, Ta = 85 °C (Fig. 1)	200	500	_	V/µs
	Critical rate of rise of commutating voltage	dv/dt(c)	Vin = 60 Vrms, I <sub>T</sub> = 15 mA (Fig. 1)	_	0.2	_	V/µs

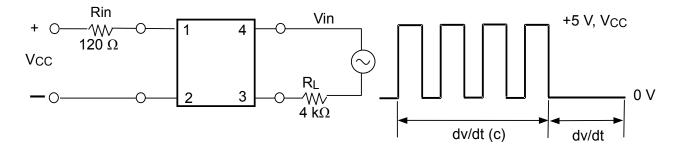
**Coupled Electrical Characteristics (Ta = 25°C)** 

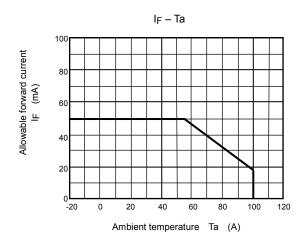
Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Trigger LED current	lfT	V <sub>T</sub> = 3 V	_	5	10	mA
Turn-on time	ton	$V_D = 3 \rightarrow 1.5 \text{ V}$ , $R_L = 20 \Omega$ IF = Rated IFTX1.5	_	30	100	μs

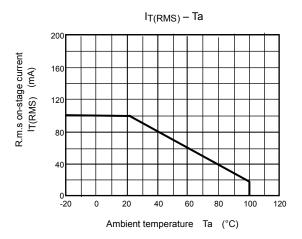
## **Isolation Characteristics (Ta = 25°C)**

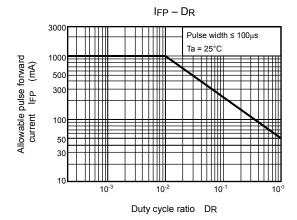
Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Capacitance (input to output)	Cs	V <sub>S</sub> = 0 V , f = 1 MHz	_	0.8	_	pF
Isolation resistance	Rs	V <sub>S</sub> = 500 V, R.H. ≤ 60 %	1×10 <sup>12</sup>	10 <sup>14</sup>	_	Ω
Isolation voltage	BVS	AC, 60 s	5000	_		Vrms

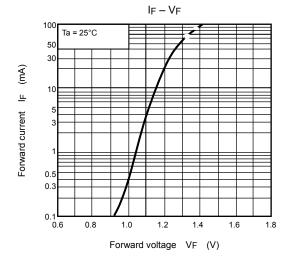
Fig. 1: dv/dt test circuit

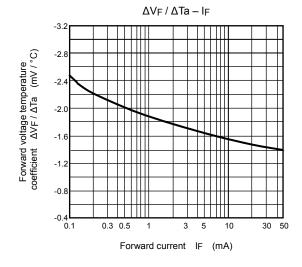


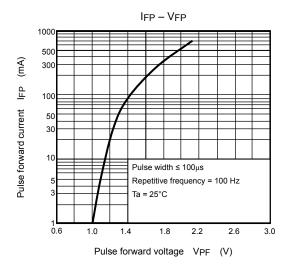




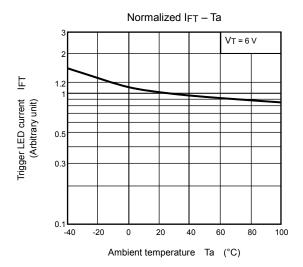


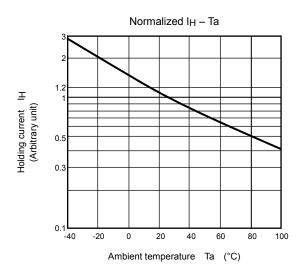


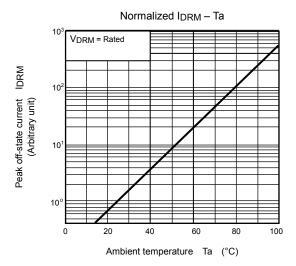


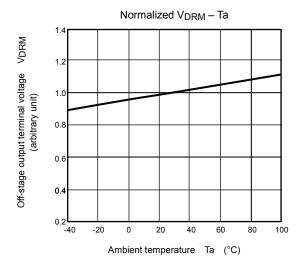


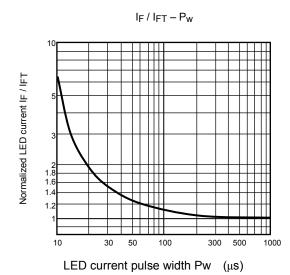
NOTE: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.











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